NPN Silicon Power Darlington

High Voltage Autoprotected

The BU323Z is a planar, monolithic, high-voltage power Darlington with a built-in active zener clamping circuit. This device is specifically designed for unclamped, inductive applications such as Electronic Ignition, Switching Regulators and Motor Control, and exhibit the following main features:

Features

Integrated High–Voltage Active Clamp

Tight Clamping Voltage Window (350 V to 450 V) Guaranteed Over the -40 C to +125 C Temperature Range

Clamping Energy Capability 100% Tested in a Live Ignition Circuit

High DC Current Gain/Low Saturation Voltages Specified Over Full Temperature Range

Design Guarantees Operation in SOA at All Times

Offered in Plastic SOT-93/TO-218 Type or TO-220 Packages Pb-Free Packages are Available*

MAXIMUM RATINGS

Rating	Symbol	Max	Unit
Collector-Emitter Sustaining Voltage	V _{CEO}	350	Vdc
Collector-Emitter Voltage	V _{EBO}	6.0	Vdc
Collector Current – Continuous – Peak	I _C I _{CM}	10 20	Adc
Base Current – Continuous – Peak	I _B I _{BM}	3.0 6.0	Adc
Total Power Dissipation @ $T_C = 25^{\circ}C$ Derate above $25^{\circ}C$	P _D	150 1.0	W W/°C
Operating and Storage Junction Temperature Range	T _J , T _{stg}	−65 to +175	°C

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	1.0	°C/W
Maximum Lead Temperature for Soldering Purposes: 1/8" from Case for 5 Seconds	ΤL	260	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

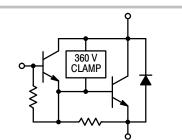
*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

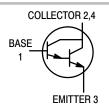


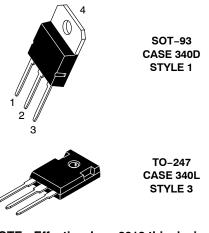
ON Semiconductor®

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10 AMPERE DARLINGTON AUTOPROTECTED 360 – 450 VOLTS CLAMP, 150 WATTS





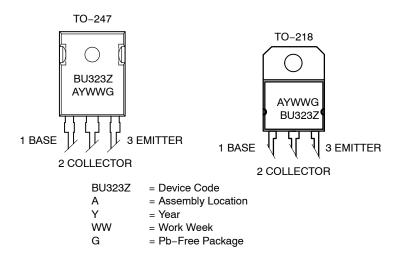


NOTE: Effective June 2012 this device will be available only in the TO-247 package. Reference FPCN# 16827.

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

MARKING DIAGRAMS



ORDERING INFORMATION

Device Order Number	Package Type	Shipping
BU323ZG	TO-218 (Pb-Free)	30 Units / Rail
BU323ZG	TO-247 (Pb-Free)	30 Units / Rail

ELECTRICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted)

	Symbol	Min	Тур	Max	Unit	
OFF CHARACTERIST	ICS (1)		•			
Collector–Emitter Cla $(T_C = -40 \text{ C to } +12)$	mping Voltage (I _C = 7.0 A) 25 C)	V _{CLAMP}	350	_	450	Vdc
Collector–Emitter Cut $(V_{CE} = 200 \text{ V}, I_B = 0)$		I _{CEO}	_	_	100	μAdc
Emitter-Base Leakag (V _{EB} = 6.0 Vdc, I _C =	r-Base Leakage Current ₃ = 6.0 Vdc, I _C = 0)			_	50	mAdo
ON CHARACTERISTIC	CS (1)		•			
Base-Emitter Saturat ($I_C = 8.0 \text{ Adc}, I_B = 0$ ($I_C = 10 \text{ Adc}, I_B = 0$	100 mAdc)	V _{BE(sat)}			2.2 2.5	Vdc
Collector–Emitter Sat ($I_C = 7.0$ Adc, $I_B = 1$ ($I_C = 8.0$ Adc, $I_B = 0$ ($I_C = 10$ Adc, $I_B = 0$	70 mAdc) (T _C = 125 C) (T _C = 125 C)	V _{CE(sat)}	- - - -	- - - -	1.6 1.8 1.8 2.1 1.7	Vdc
Base-Emitter On Volt ($I_C = 5.0 \text{ Adc}, V_{CE}$ ($I_C = 8.0 \text{ Adc}, V_{CE}$	tage = 2.0 Vdc) (T _C = -40 C to +125 C)	V _{BE(on)}	1.1 1.3		2.1 2.3	Vdc
Diode Forward Voltag (I _F = 10 Adc)	je Drop	V _F	_	_	2.5	Vdc
DC Current Gain $(I_C = 6.5 \text{ Adc}, V_{CE})$ $(I_C = 5.0 \text{ Adc}, V_{CE})$	h _{FE}	150 500		_ 3400	_	
OYNAMIC CHARACTE	ERISTICS		•			
Current Gain Bandwi (I _C = 0.2 Adc, V _{CE}	f _T	-	_	2.0	MHz	
Output Capacitance (V _{CB} = 10 Vdc, I _E =	C _{ob}	_	_	200	pF	
Input Capacitance (V _{EB} = 6.0 V)	C _{ib}	_	_	550	pF	
CLAMPING ENERGY	(see notes)		•	•	•	•
Repetitive Non-Destructive Energy Dissipated at turn-off: (I _C = 7.0 A, L = 8.0 mH, R _{BE} = 100 Ω) (see Figures 2 and 4)		W _{CLAMP}	200	_	-	mJ
SWITCHING CHARAC	TERISTICS: Inductive Load (L = 10 mH)					
Fall Time	(I _C = 6.5 A, I _{B1} = 45 mA,	t _{fi}	-	625	-	ns
Storage Time	$V_{BE(off)} = 0, R_{BE(off)} = 0,$	t _{si}	-	10	30	μs
Cross-over Time	V _{CC} = 14 V, V _Z = 300 V)	t _c	-	1.7	-	μs

1. Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle = 2.0%.

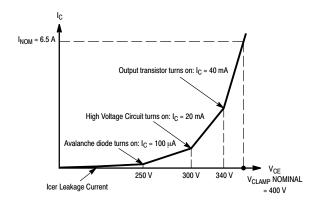


Figure 1. I_C = f(V_{CE}) Curve Shape

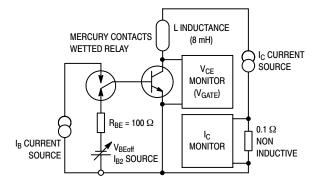


Figure 2. Basic Energy Test Circuit

By design, the BU323Z has a built–in avalanche diode and a special high voltage driving circuit. During an auto–protect cycle, the transistor is turned on again as soon as a voltage, determined by the zener threshold and the network, is reached. This prevents the transistor from going into a Reverse Bias Operating limit condition. Therefore, the device will have an extended safe operating area and will always appear to be in "FBSOA." Because of the built–in zener and associated network, the $I_C = f(V_{CE})$ curve exhibits an unfamiliar shape compared to standard products as shown in Figure 1.

The bias parameters, V_{CLAMP} , I_{B1} , $V_{BE(off)}$, I_{B2} , I_C , and the inductance, are applied according to the Device Under Test (DUT) specifications. V_{CE} and I_C are monitored by the test system while making sure the load line remains within the limits as described in Figure 4.

Note: All BU323Z ignition devices are 100% energy tested, per the test circuit and criteria described in Figures 2 and 4, to the minimum guaranteed repetitive energy, as specified in the device parameter section. The device can sustain this energy on a repetitive basis without degrading any of the specified electrical characteristics of the devices. The units under test are kept functional during the complete test sequence for the test conditions described:

 $I_{C(peak)} = 7.0 \text{ A}, I_{C}H = 5.0 \text{ A}, I_{C}L = 100 \text{ mA}, I_{B} = 100 \text{ mA}, R_{BE} = 100 \Omega, V_{gate} = 280 \text{ V}, L = 8.0 \text{ mH}$

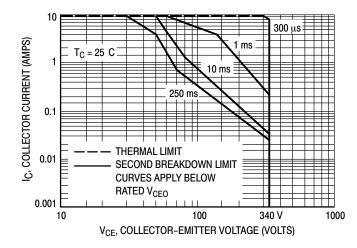
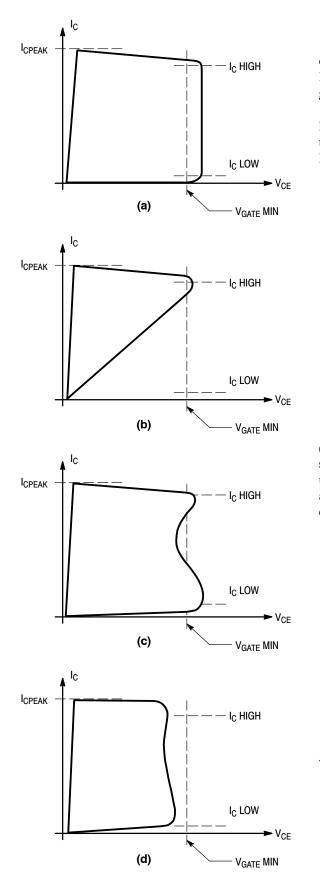


Figure 3. Forward Bias Safe Operating Area



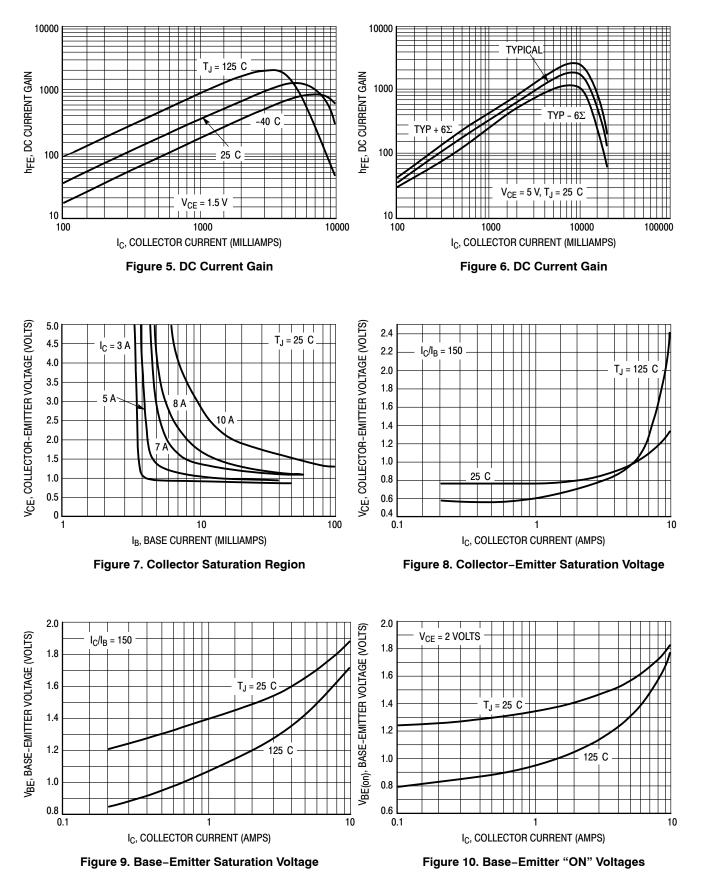
The shaded area represents the amount of energy the device can sustain, under given DC biases $(I_C/I_B/V_{BE(off)}/R_{BE})$, without an external clamp; see the test schematic diagram, Figure 2.

The transistor PASSES the Energy test if, for the inductive load and $I_{CPEAK}/I_B/V_{BE(off)}$ biases, the V_{CE} remains outside the shaded area and greater than the V_{GATE} minimum limit, Figure 4a.

The transistor FAILS if the V_{CE} is less than the V_{GATE} (minimum limit) at any point along the V_{CE}/I_C curve as shown on Figures 4b, and 4c. This assures that hot spots and uncontrolled avalanche are not being generated in the die, and the transistor is not damaged, thus enabling the sustained energy level required.

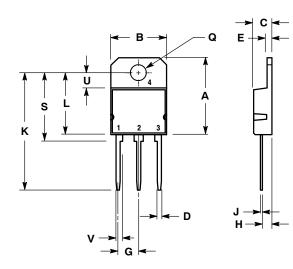
The transistor FAILS if its Collector/Emitter breakdown voltage is less than the V_{GATE} value, Figure 4d.





PACKAGE DIMENSIONS

SOT-93 (TO-218) CASE 340D-02 **ISSUE E**



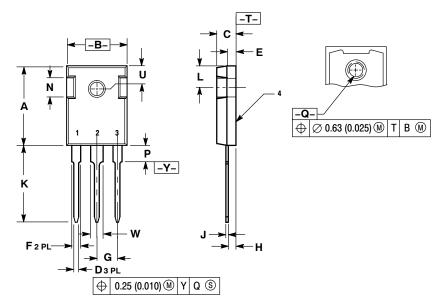
NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: MILLIMETER.

	MILLIMETERS		INCHES		
DIM	MIN	MAX	MIN	MAX	
Α		20.35		0.801	
В	14.70	15.20	0.579	0.598	
С	4.70	4.90	0.185	0.193	
D	1.10	1.30	0.043	0.051	
Е	1.17	1.37	0.046	0.054	
G	5.40	5.55	0.213	0.219	
Н	2.00	3.00	0.079	0.118	
ſ	0.50	0.78	0.020	0.031	
κ	31.00	REF	1.220 REF		
L		16.20		0.638	
Q	4.00	4.10	0.158	0.161	
S	17.80	18.20	0.701	0.717	
U	4.00 REF		0.157	' REF	
V	1.75 REF 0.069				
STYLE 1: PIN 1. BASE					
2. COLLECTOR 3. EMITTER					
4 0011 50700					

COLLECTOR

4.

TO-247 CASE 340L-02 ISSUE F



NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: MILLIMETER.

	MILLIMETERS		INC	HES	
DIM	MIN	MAX	MIN	MAX	
Α	20.32	21.08	0.800	8.30	
В	15.75	16.26	0.620	0.640	
c	4.70	5.30	0.185	0.209	
D	1.00	1.40	0.040	0.055	
Е	1.90	2.60	0.075	0.102	
F	1.65	2.13	0.065	0.084	
G	5.45 BSC		0.215 BSC		
Η	1.50	2.49	0.059	0.098	
-	0.40	0.80	0.016	0.031	
K	19.81	20.83	0.780	0.820	
L	5.40	6.20	0.212	0.244	
Ν	4.32	5.49	0.170	0.216	
Ρ		4.50		0.177	
Ø	3.55	3.65	0.140	0.144	
U	6.15 BSC		0.242	BSC	
W	2.87	3.12	0.113	0.123	

STYLE 3: PIN 1. BASE 2. COLLECTOR 3. EMITTER 4. COLLECTOR

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